



# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**

[List multiple models if applicable.]

HP TouchSmart IQ500/IQ504/IQ505/IQ506/IQ507/IQ510 series PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	10
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	4
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		3
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

### 1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
JAN_MAIN_REAR_COVER	JAN_MAIN_REAR_COVER	267g	>ABS<	
JAN_CHIN	JAN_CHIN	118.25g	>ABS<	
JAN_SIDE_CAP_RT	JAN_SIDE_CAP_RT	28.2g	>PMMA<	
JAN_SIDE_CAP_RT	JAN_SIDE_CAP_RT	28.2g	PC+ABS	
JAN_SIDE_CAP_LF	JAN_SIDE_CAP_LF	29.5g	>PMMA<	
JAN_SIDE_CAP_LF	JAN_SIDE_CAP_LF	29.5g	>PC+ABS<	
JAN_REAR_PANEL	JAN_REAR_PANEL	372g	>ABS<	
JAN_LOWER_REAR_COVER	JAN_LOWER_REAR_COVER	99.9g	>ABS<	
JAN_OUTER_BEZEL	JAN_OUTER_BEZEL	112.6g	>ABS<	
JAN_INNER_BEZEL	JAN_INNER_BEZEL	93.6g	>ABS<	
JAN_AMBIENT_LIGHT_FILLER	JAN_AMBIENT_LIGHT_FILLER	25.5g	>ABS<	
JAN_SIDE_CAP_LF_NON_AMB	JAN_SIDE_CAP_LF_NON_AMB	29g	>PMMA<	
JAN_SIDE_CAP_LF_NON_AMB	JAN_SIDE_CAP_LF_NON_AMB	29g	>PC+ABS<	

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 M3 Screwdriver	
Description #2 M2 Screwdriver	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. See detailed instructions attached below
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).